

BCM

Product Change Notice

PCN Number: P221907		Revision: A		Date of Publication: 05/09/2022		
PRODUCT NAME	PRODUCT PART#	OLD — RE	E V. — NEW		REVISION TY	/PE
/IX170QD	71134-IA	2.0/ 1.50	2.0/ 2.00	Hardware/ BIOS	5	
/X170QD-QC	71133	2.0/ 1.50	2.0/ 2.00			
/X170QD-UL	71135-IA	2.0/ 1.50	2.0/ 2.00			
MX170QD-F	71137-IA	2.0/ 1.50	2.0/ 2.00			
REASON OF CHANG))E:					
1) Current Infine	on PX3517 MOSFET	Driver will be	End of Life.			
2) Analog Device	es AD5258 is highly co	onstrained and	d severely imp	acting productio	n lead-time.	It's function as a
DC power cor	ntrol for the LVDS pan	nel brightness	has been repla	ced by the more	e common PW	M control.
3) Current ANPE	C APL3540 and APL3	542 Power Co	ntroller will be	End of Life.		
ESCRIPTION OF C	HANGE:					
1) Re-spin PCB c	hanging to use Mond	olithic Power S	Systems (MPS)	MP2979A PWM	Controller and	1 MP86990 Powe
MOSFET and	Driver.					
2) Remove Anal	og Devices AD5258 D	igital Potentio	meter for DC o	control on LVDS	Panel.	
, 0	e MPS MP5921 Powe					
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APPROVED BY

VP OF SALES		05/09/2022
	Signature	Date